

# **iMAPS New England – 45<sup>th</sup> Symposium & Expo**

**The Largest Regional Symposium Dedicated to  
Microelectronics, Assembly and Packaging  
Boxboro Regency Hotel & Conference Center**

**Boxborough, Massachusetts**

**May 1, 2018**

**Technical Co-Chairs**

**Lee Levine, PSC & Dave Saums, DS&A**



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**DEADLINE EXTENDED TO JANUARY 31, 2018**

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**Please e-mail your 250 word abstract to:**

**Lee Levine, PSC - [levilr@ptd.net](mailto:levilr@ptd.net)**

**~~Deadline for Submission – December 31, 2017~~**

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